

## Message Text

CONFIDENTIAL

PAGE 01 STATE 210941  
ORIGIN EB-08

INFO OCT-01 EUR-12 ISO-00 DODE-00 NSAE-00 ICA-11  
TRSE-00 SOE-02 DOE-15 CIAE-00 COME-00 /049 R

DRAFTED BY EB/ITP/EWT:CECOLE  
APPROVED BY EB/ITP/EWT:RPRACHT  
COMMERCE/OEA:MKRAVETZ  
-----055829 191012Z /12

R 182150Z AUG 78  
FM SECSTATE WASHDC  
TO AMEMBASSY PARIS

C O N F I D E N T I A L STATE 210941

USOECD, EXCON

E.O. 11652: GDS

TAGS: ESTC, COCOM, US, HU

SUBJECT: U.S. EXPORT OF ASSEMBLY AND TEST EQUIPMENT FOR  
SEMICONDUCTORS - IL1355

REF:A. COCOM DOC (78) 594 B. 78 PARIS 25215

THE APPLICANT (FAIRCHILD) HAS ASSURED US IN EACH TRANSACT-  
ION AND CERTIFIED IN WRITTING THAT THE TUNGSRAM PROJECT IS  
DEVOTED TO THE ASSEMBLY AND PACKAGING OF FAIRCHILD CHIPS  
IN PLASTIC PACKAGES. KNOWING THIS CIRCUMSTANCE, THE U.S.  
CAN EASILY ACCEPT THE GERMAN CONDITION. VANCE

CONFIDENTIAL

NNN

## Message Attributes

**Automatic Decaptioning:** X  
**Capture Date:** 01 jan 1994  
**Channel Indicators:** n/a  
**Current Classification:** UNCLASSIFIED  
**Concepts:** STRATEGIC TRADE CONTROLS, EXPORT LICENSES  
**Control Number:** n/a  
**Copy:** SINGLE  
**Draft Date:** 18 aug 1978  
**Decaption Date:** 01 jan 1960  
**Decaption Note:**  
**Disposition Action:** RELEASED  
**Disposition Approved on Date:**  
**Disposition Case Number:** n/a  
**Disposition Comment:** 25 YEAR REVIEW  
**Disposition Date:** 20 Mar 2014  
**Disposition Event:**  
**Disposition History:** n/a  
**Disposition Reason:**  
**Disposition Remarks:**  
**Document Number:** 1978STATE210941  
**Document Source:** CORE  
**Document Unique ID:** 00  
**Drafter:** CECOLE  
**Enclosure:** n/a  
**Executive Order:** GS  
**Errors:** N/A  
**Expiration:**  
**Film Number:** D780339-1384  
**Format:** TEL  
**From:** STATE  
**Handling Restrictions:** n/a  
**Image Path:**  
**ISecure:** 1  
**Legacy Key:** link1978/newtext/t19780847/aaaabmqe.tel  
**Line Count:** 43  
**Litigation Code IDs:**  
**Litigation Codes:**  
**Litigation History:**  
**Locator:** TEXT ON-LINE, ON MICROFILM  
**Message ID:** f04ae360-c288-dd11-92da-001cc4696bcc  
**Office:** ORIGIN EB  
**Original Classification:** CONFIDENTIAL  
**Original Handling Restrictions:** n/a  
**Original Previous Classification:** n/a  
**Original Previous Handling Restrictions:** n/a  
**Page Count:** 1  
**Previous Channel Indicators:** n/a  
**Previous Classification:** CONFIDENTIAL  
**Previous Handling Restrictions:** n/a  
**Reference:** n/a  
**Retention:** 0  
**Review Action:** RELEASED, APPROVED  
**Review Content Flags:**  
**Review Date:** 19 may 2005  
**Review Event:**  
**Review Exemptions:** n/a  
**Review Media Identifier:**  
**Review Release Date:** n/a  
**Review Release Event:** n/a  
**Review Transfer Date:**  
**Review Withdrawn Fields:** n/a  
**SAS ID:** 1689335  
**Secure:** OPEN  
**Status:** NATIVE  
**Subject:** U.S. EXPORT OF ASSEMBLY AND TEST EQUIPMENT FOR SEMICONDUCTORS - IL1355  
**TAGS:** ESTC, HU, US, COCOM  
**To:** PARIS  
**Type:** TE  
**vdkgvwkey:** odb://SAS/SAS.dbo.SAS\_Docs/f04ae360-c288-dd11-92da-001cc4696bcc  
**Review Markings:**  
Sheryl P. Walter  
Declassified/Released  
US Department of State  
EO Systematic Review  
20 Mar 2014  
**Markings:** Sheryl P. Walter Declassified/Released US Department of State EO Systematic Review 20 Mar 2014